SCAS784A – OCTOBER 2004 – REVISED JANUARY 2008

- Qualified for Automotive Applications
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 9.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible

description/ordering information

The SN74ACT10 device contains three independent 3-input NAND gates. The device performs the Boolean functions $Y = \overline{A \cdot B \cdot C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

D OR PW PACKAGE (TOP VIEW)							
1A	1	υ	14	\mathbf{h}	Vaa		
1B			13	K.	V _{CC} 1C		
	2			F.	1C		
2A	3		12	Ц	1Y		
2B	4		11		ЗA		
2C	5		10		3B		
2Y	6		9		3C		
GND	7		8		3Y		

ORDERING INFORMATION[†]

TA	PACKAG	E‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 125°C	SOIC – D	Tape and reel	SN74ACT10QDRQ1§	ACT10Q	
-40°C to 125°C	TSSOP – PW	Tape and reel	SN74ACT10QPWRQ1	ACT10Q	

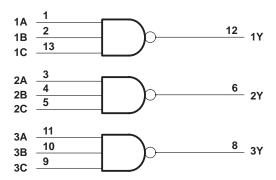
[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

[‡]Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

§ Product Preview

FUNCTION TABLE (each gate)							
	INPUTS	OUTPUT					
Α	В	С	Y				
Н	Н	Н	L				
L	Х	Х	н				
Х	L	Х	н				
Х	Х	L	Н				

logic diagram, each gate (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	5 V 5 V mA mA mA MA C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
\vee_{I}	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
TA	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST CONDITIONS	TEST CONDITIONS V _{CC}		A = 25°C	;	T _A = −40°C to 125°C		T _A = −40°C to 85°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
	504	4.5 V	4.4	4.49		4.4		4.4			
	I _{OH} = –50 μA	5.5 V	5.4	5.49		5.4		5.4			
		4.5 V	3.86			3.7		3.76		V	
VOH	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V	
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85					
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		7	
	I _{OL} = 50 μA	4.5 V		0.001	0.1		0.1		0.1	v	
		5.5 V		0.001	0.1		0.1		0.1		
		4.5 V			0.36		0.5		0.44		
V _{OL}	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44		
	I _{OL} = 50 mA [†]	5.5 V					1.65				
	I _{OL} = 75 mA [†]	5.5 V							1.65		
lj	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ	
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		80		40	μA	
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.6			1.6		1.5	mA	
Ci	$V_{I} = V_{CC}$ or GND	5 V		2.6						pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[±] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

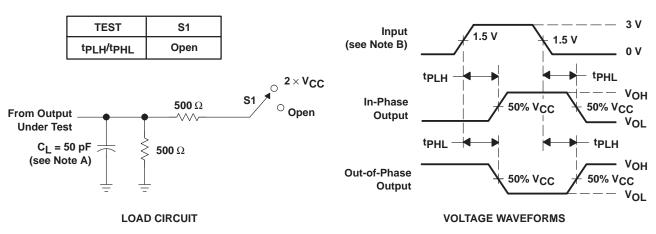
PARAMETER	FROM (INPUT)	TO (OUTPUT)	т,	₄ = 25°C	;	T _A = -4 125		T _A = -4 85°		UNIT
	(INPUT)	(001P01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A	N N	1	6.5	9	1	10	1	10	
^t PHL	Any	Ŷ	1	6.5	9	1	9.5	1	9.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST	TYP	UNIT	
C _{pd} Po	wer dissipation capacitance	C _L = 50 pF,	f = 1 MHz	25	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns. C. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ACT10QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT10QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74ACT10-Q1 :

Catalog: SN74ACT10

• Military: SN54ACT10

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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